

<b>PATENT ASSIGNMENT COVER SHEET</b>
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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
CHIA-TA YU	09/15/2017
KAI-HSUAN LEE	09/15/2017
YEN-MING CHEN	09/15/2017
CHI ON CHUI	09/20/2017
SAI-HOOI YEONG	09/15/2017
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.
<b>Street Address:</b>	NO. 8, LI-HSIN RD. 6
<b>Internal Address:</b>	HSINCHU SCIENCE PARK
<b>City:</b>	HSINCHU
<b>State/Country:</b>	TAIWAN
<b>Postal Code:</b>	300-78
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	16722630
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(214)200-0853
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	214-651-5000
<b>Email:</b>	ipdocketing@haynesboone.com
<b>Correspondent Name:</b>	HAYNES AND BOONE, LLP IP SECTION
<b>Address Line 1:</b>	2323 VICTORY AVENUE
<b>Address Line 2:</b>	SUITE 700
<b>Address Line 4:</b>	DALLAS, TEXAS 75219
<b>ATTORNEY DOCKET NUMBER:</b>	20161298 / 24061.3565US03
<b>NAME OF SUBMITTER:</b>	SVJETLANA LONG
<b>SIGNATURE:</b>	/Svjetlana Long/
<b>DATE SIGNED:</b>	12/20/2019

**Total Attachments: 3**

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**ASSIGNMENT**

WHEREAS, we,

- (1) Chia-Ta YU of New Taipei City, Taiwan
- (2) Kai-Hsuan LEE of Hsinchu City, Taiwan
- (3) Yen-Ming CHEN of Hsin-Chu County
- (4) Chi On CHUI of Hsinchu City, Taiwan
- (5) Sai-Hooi YEONG of Hsinchu County

have invented certain improvements in

**INTERCONNECT STRUCTURE FOR SEMICONDUCTOR DEVICE AND METHODS OF FABRICATION THEREOF**

for which we have executed an application for Letters Patent of the United States of America,

  X   of even date filed herewith; and  
           filed on                    and assigned application number                   ; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Co., Ltd., ("TSMC"), 8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, Republic of China, is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: **Chia-Ta YU**

Residence Address: 8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, Republic of China

Dated: 09.15.2017

Chia-Ta Yu  
Inventor Signature

Inventor Name: **Kai-Hsuan LEE**

Residence Address: 7F, No. 55, Ln. 19, Guanxin Rd., East Dist., Hsinchu City 300, Taiwan, Republic of China

Dated: 09.15.2017

Kai-Hsuan Lee  
Inventor Signature

Inventor Name: **Yen-Ming CHEN**

Residence Address: 6F, No. 33, Sheng-Li, 5<sup>th</sup> Rd., Chu-Pei City, Hsin-Chu County, Taiwan Republic of China

Dated: 9/15.2017

Yen-Ming Chen  
Inventor Signature

Inventor Name: **Chi On CHUI**

Residence Address: Room 10-1, 10/F, 213 Guanxin Rd., East Dist., Hsinchu City 30072 Taiwan, Republic of China

Dated: 9/20/2017

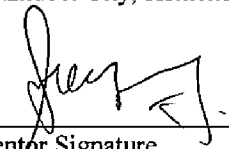
Chi On Chui  
Inventor Signature

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Inventor Name: **Sai-Hooi YEONG**

Residence Address: 6F.-2, No. 128, Sec. 1, Liujiia 1<sup>st</sup> Rd, Zhubei City, Hsinchu County 302,  
Taiwan, Republic of China

Dated: 07/15/2017

  
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Inventor Signature